UNITS: um | Prepreg > Pressed um < Copper | Dk Frequency: 500 MHz | Impedance: ohms | Total Board Thickness: 2321.56 um

Layer No.	Via	Description	Layer Name	Material Type	Dielectric Constant	Dielectric Thickness	Copper Thickness	Trace Clearance	Trace Width	Current (Amps)	Characteristic Impedance (Zo)	Edge Coupled Differential (Zdiff)	Broadside Coupled Differential (Zdbs)	Notes
		Soldermask		Dielectric	3.3	12.7								
1	250	Signal	Top	Conductive			35.56	175	160	0.43	56.45	97.23		
		Prepreg		370HR; 2116; Rc= 56% (500 MHz)	4.1	121.92								Tg=180C; Df=0.0178
2		Plane	GND	Conductive			17.78							
		Core		370HR; 2-2116; Rc=47% (500 MHz)	4.3	203.2								Tg=180C; Df=0.016
3		Signal	Inner 3	Conductive			17.78	150	125	0.22	58.1	97.42		
		Prepreg		370HR; 2116; Rc= 56% (500 MHz)	4.1	121.92								Tg=180C; Df=0.0178
		Prepreg		370HR; 2116; Rc= 56% (500 MHz)	4.1	121.92								Tg=180C; Df=0.0178
4		Plane	GND	Conductive			35.56							
		Core		370HR; 2-2116/7628; Rc=46% (500 MHz)	4.3	406.4								Tg=180C; Df=0.016
5		Plane	VCC	Conductive			35.56							
		Prepreg		370HR; 2116; Rc= 56% (500 MHz)	4.1	121.92								Tg=180C; Df=0.0178
6		Plane	VCC	Conductive			35.56							
		Core		370HR; 2-2116/7628; Rc=46% (500 MHz)	4.3	406.4								Tg=180C; Df=0.016
7		Plane	GND	Conductive			35.56							
		Prepreg		370HR; 2116; Rc= 56% (500 MHz)	4.1	121.92								Tg=180C; Df=0.0178
		Prepreg		370HR; 2116; Rc= 56% (500 MHz)	4.1	121.92								Tg=180C; Df=0.0178
8		Signal	Inner 8	Conductive			17.78	150	125	0.22	58.1	97.42		
		Core		370HR; 2-2116; Rc=47% (500 MHz)	4.3	203.2								Tg=180C; Df=0.016
9		Plane	GND	Conductive			17.78							
		Prepreg		370HR; 2116; Rc= 56% (500 MHz)	4.1	121.92								Tg=180C; Df=0.0178
10		Signal	Bottom	Conductive			35.56	175	160	0.43	56.45	97.23		
		Soldermask		Dielectric	3.3	12.7								

Target Impedance	Tol +/-%	Layer No.	Trace Clearance	Trace Width	Current (Amps)	Characteristic Impedance (Zo)	Edge Coupled Differential (Zdiff)	Broadside Coupled Differential (Zdbs)	Notes
Pair 1	10	1	175	160	0.43	56.45	97.23		
Pair 1	10	3	150	125	0.22	58.1	97.42		
Pair 1	10	8	150	125	0.22	58.1	97.42		
Pair 1	10	10	175	160	0.43	56.45	97.23		

Via Span Definitions					
From	To	Hole Size	Tol +/-	Aspect Ratio	Via Type
1	10	250	50	9.26:1	PTH

Company:	Nikhef		**ICD Stackup Planner**
Project Name:	Timing Main Board	**Fabricator::**	
Designer/Email:	charles.ietswaard@nikhef.nl	Contact/Email:	charles.ietswaard@nikhef.nl
SP File Name::	10 Layer-HyperLynx.stk	Design Revision:	V1.0
Excel File Name::	10 Layer-HyperLynx.xlsx	Date::	17-12-2021